



Data Sheet

Customer:	
Part No:	CL-SFC508WBGR-6.5K-02
Sample No:	
Description:	
Item No:	

Customer						
Check Inspection Approval Date						





Features

■ Package Size: $5.0(L) \times 5.4(W) \times 1.8(T)$ mm

■ Silicone Packed

■ Suitable for different working environment

■ Super long lifetime: 50000HRs

■ Anti UV

■ White colors are available in(2300K- 25000K)

■ Wide viewing angle $(2^{\theta} 1/2 = 120^{\circ})$

Device Selection Guide

ITEM	MATERIALS
Resin	Silicon
Bonding wire	25 Em Au
Lens color	Water Clear
Dice	InGaN

Applications

■ Indoor lighting: Fluorescent lamp, tube

 Commercial illumination and displays: Advertising words, light box

LCD Backlighting

■ Decorative lighting: light strip

Automotive interior auxiliary lighting

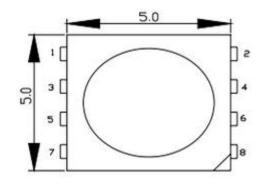
Other illumination and displays

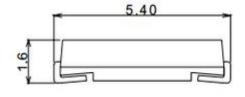


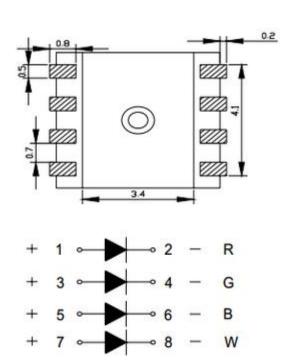


REFLECTOR COATING TYPE HIGH-PERFORMANCE LEDs

High Performance SMD Single-Color Top LEDs







NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are 0.2mm (0.008inch) unless otherwise noted





Absolute maximum ratings

(TA=25°C)

Paramete	Symbol	Rat	Unit
Forward current	I F	20	mA
Reverse voltage	VR	5	V
Power dissipation	Pd	300	mW
Operating Temperature	ТОР	-20 ~+80	${\mathbb C}$
Storage Temperature	Tstg	-40 ~+80	${\mathfrak C}$
Peak Forward Current (Duty 1/10 @ 1KHz)	IFP	20	mA
Lead Soldering Temperature (5mm From Body)	TSOI	260℃ For 5 Seconds)/℃	

Electro-optical characteristics

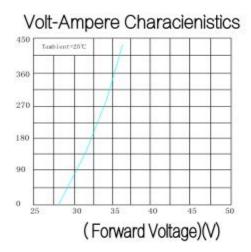
 $(TA=25^{\circ}C)$

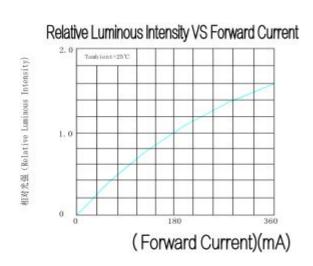
D	Test Condition		Symbo	Value			T T •4
Parameter			Symbo	Min	Avg	Max	Unit
F1 -14	I F =20mA	R	Vf	1.9	2.1	2.3	v
Forward voltage	I F =20mA	G	Vf	2.8	3.0	3.2	v
	I F =20mA	В	Vf	2.8	3.0	3.2	v
	I F =20mA	W	Vf	2.8	3.0	3.2	v
Wavelength	I F =20mA	R	nm	621.5		626	nm
wavelength	I F =20mA	G	nm	520.5		525	nm
	I F =20mA	В	nm	460		464.5	nm
Luminous intensity	I F =20mA	R	mcd	600		800	mcd
Luminous intensity	I F =20mA	G	mcd	1200		1600	mcd
	I F =20mA	В	mcd	400		600	mcd
Color Temperature	I F =20mA	W	TC	6000		7000	K
Luminous Flux	I F =20mA	W	ф	6		8	Lm
Viewing Angle			2θ1/2		120		deg
Reverse Current			IR			10	EA

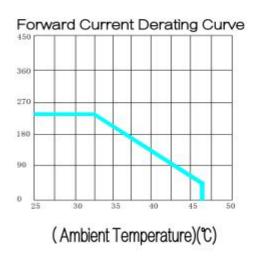


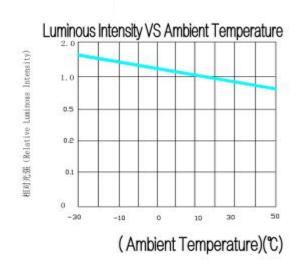


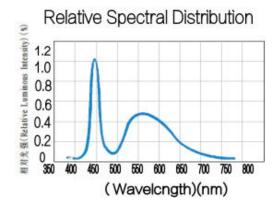
(Optical-Electrical Characteristic)

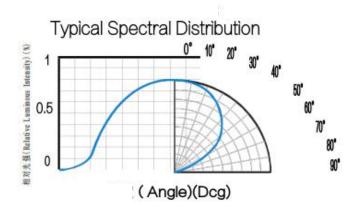
















Reliability Test Items And Conditions

TestItems	Reference	Reference Test Conditions Time		Quantity	Criterion
Thermal Shock	MIL-STD-202G	-40°C (30min) -100°C (30min)	100Cycles	22	0/22
Temperature	JEITA ED-4701 200 203	-10℃~65℃; 0%~90%RH	10cycles	22	0/22
High temperature storage	JEITA ED -4071 200 201	Ta=100℃	1000H	22	0/22
Low temperature storage	JEITA ED -4071 200 202	Ta=-40°C	1000H	22	0/22
High temperature high humidity sto	JEITA ED -4071 prage 100 103	Ta=60°C; RH=90%	1000H	22	0/22
High temperature life	JESD22-A108D	Ta=80℃	1000Н	22	0/22
Normal temperatur life test	e JESD22-A108D	Ta=25℃ IF=150mA	1000Н	22	0/22
Resistance to soldering heat	GB/T 4937, II , 2.2&2.3	Tsol*=(240±5)°C 10secs	2 times	22	0/22

Criteria For Judging Damage

TestItems	Symbol	Test Conditions	Criteria For Judging Damage
ForwardVoltage	VF	I F =I FT	Initial Data±10%
RecerseCurrent	I R	V R =5V	IR ≤10uA
LuminousIntensity	IV	I F =I FT	Average I V attenuation \leq 30%; single I V attenuation \leq 50%
Resistance to soldering heat			No cracks inside the material, no material bursting, peeling, no death light

*Note Tsol-Temperature of tin liquid



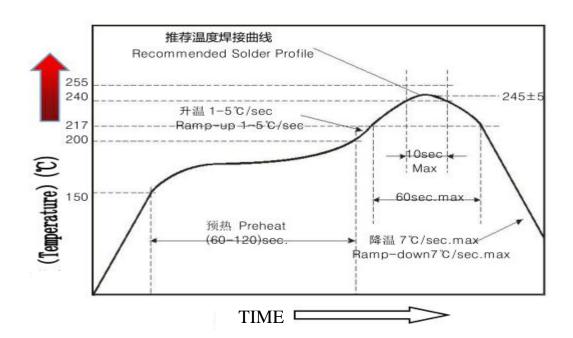


(Useful hint):

1, Hand Soldering

A soldering iron of less than 20W is recommended to be used in Hand Soldering. Please keep the temperature fo the soldering iron under $360\,^{\circ}$ C while soldering. Each terminal fo the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering. 2.Reflow Soldering: Use the conditions shown in the under Figure of Pb-Free Reflow Soldering



- Reflow soldering only allowed to do once
- Stress on the LEDs should be avoided during heating in soldering process
- After soldering, do not deal with the product before its temperature drop down to room Temperature.





Precautions(1)

1. Storage

- Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to aminimum.
- Before opening the package, the product should be kept at 30°C or less and humidity less than 60% RH, and beused within a year.
- After opening the package, the product should be stored at 30°C or less and humidity less than 10%RH, and besoldered within 24 hours (1day). It is recommended that the product be operated at the workshop condition of 30°C or less and humidity less than 60%RH.
- If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: $(70\pm5)^{\circ}$ °C for 24 hours.

2. Static Electricity

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.





Precautions (2)

3. Vulcanization

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag2S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline, seriously affecting the performance of the product. So we should take corresponding measures to avioding vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.

4. Safety Advice For Human Eyes

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity will cause great hazard to human eyes. Please be careful.





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Luminous Intensity Bin Limits

BIN Code	Test Condition @20mA			
UHR	Vfmin(v)	Vfmax (v)		
1	2.0	2.2		
DLG	Vfmin(v)	Vfmax (v)		
1	3.0	3.2		
DNB	Vfmin(v)	Vfmax (v)		
1	3.0	3.2		
DBW	Vfmin(v)	Vfmax (v)		
1	3.0	3.2		

Forward Voltage Bin Limits

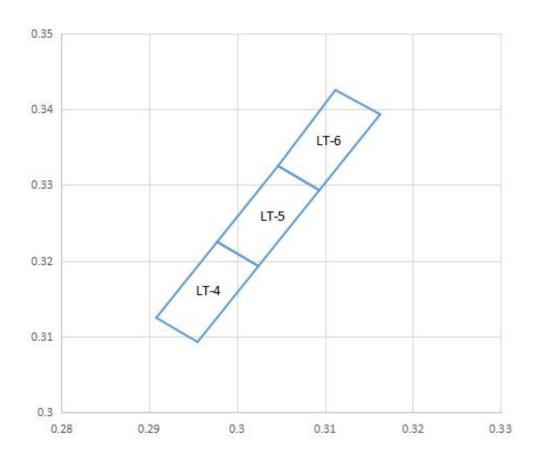
BIN Code	Test condition	on: @20mA
UHR	IVmin(mcd)	IVmax (mcd)
1	600	700
2	700	800
DLG	IVmin(mcd)	IVmax (mcd)
1	1200	1400
2	1400	1600
DNB	IVmin(mcd)	IVmax (mcd)
1	400	500
2	500	600
DBW	IVmin(lm)	IVmax (lm)
1	6	7
2	7	8

Dominant Wavelength BIN Limits

BIN Code	Test condition: @20mA			
UHR	λ _{dmin} (nm)	λ _{dmax} (nm)		
1	621.5	623		
2	623	624.5		
3	624.5	626		
DLG	λ _{dmin} (nm)	λ _{dmax} (nm)		
1	520.5	522		
2	522	523.5		
3	523.5	525		
DNB	λ _{tmin} (nm)	λ _{dmax} (nm)		
1	460	461.5		
2	461.5	463		
3	463	464.5		







Bin code	Х	у	Bin code	х	у	Bin code	х	у
	0.2908	0.3125		0.2977	0.3225		0.3047	0.3325
174	0.2955	0.3093	LTE	0.3024	0.3193		0.3094	0.3293
LT-4	0.3024	0.3193	LT-5	0.3094	0.3293	LT-6	0.3163	0.3393
İ	0.2977	0.3225		0.3047	0.3325		0.3112	0.3425